## **UNR51A6G**

### Silicon PNP epitaxial planar type

#### For digital circuits

#### ■ Features

- Costs can be reduced through downsizing of the equipment and reduction of the number of parts.
- SMini type package allowing easy automatic insertion through tape packing

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-50	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V	
Collector current	$I_{\rm C}$	-80	mA	
Total power dissipation	$P_{T}$	150	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	$T_{\rm stg}$ $-55 \text{ to } +150$		°C	

#### ■ Package

- Code
- SMini3-F2
- Pin Name
  - 1: Base
  - 2: Emitter
  - 3: Collector

#### ■ Marking Symbol: CN

#### ■ Internal Connection

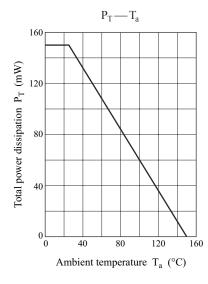
$$B \circ \xrightarrow{R_1 (4.7 \text{ k}\Omega)} C$$

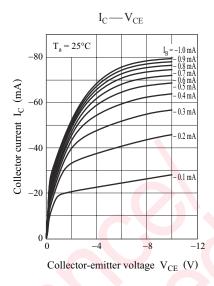
#### ■ Electrical Characteristics T<sub>a</sub> = 25°C±3°C

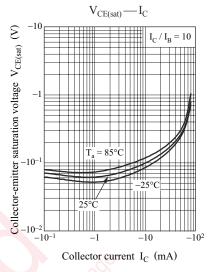
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_{\rm C} = -10 \mu{\rm A}, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{\rm CB} = -50  \text{V},  I_{\rm E} = 0$			- 0.1	μА
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = -50 \text{ V}, I_{B} = 0$			- 0.5	μА
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -6 \text{ V}, I_C = 0$			-0.01	mA
Forward current transfer ratio	$h_{\mathrm{FE}}$	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	160		460	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -0.3 \text{ mA}$			- 0.25	V
Output voltage high-level	$V_{OH}$	$V_{CC} = -5 \text{ V}, V_{B} = -0.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$	-4.9			V
Output voltage low-level	V <sub>OL</sub>	$V_{CC} = -5 \text{ V}, V_{B} = -2.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$			- 0.2	V
Input resistance	$R_1$		-30%	4.7	+30%	kΩ
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

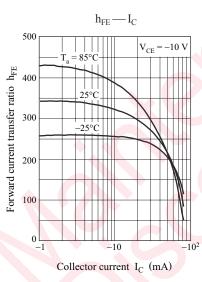
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

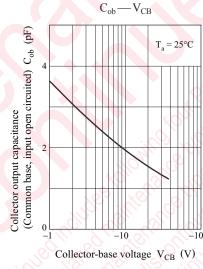
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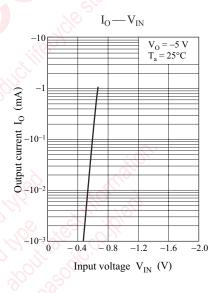


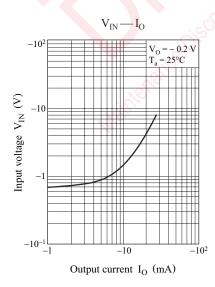








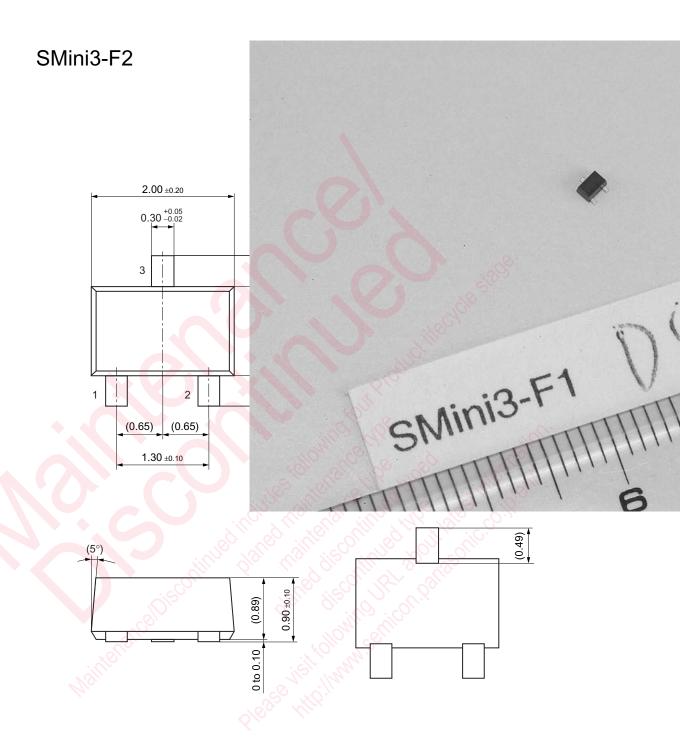




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